

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Detuns	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21276sdfp-v2

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/26 Group and Table 1.2 outlines the Functions and Specifications for R8C/27 Group.

	ltem	Specification
CPU	Number of	89 instructions
	fundamental	
	instructions Minimum instruction	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) (other than K version)
	Minimum instruction	
	execution time	62.5 ns (f(XIN) = 16 MHz, VCC = 3.0 to 5.5 V) (K version) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V)
		200 ns (f(XIN) = 5 MHz, VCC = 2.2 to 5.5 V) (N, D version)
	Operating mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.3 Product Information for R8C/26 Group
Peripheral	Ports	I/O ports: 25 pins, Input port: 3 pins
Functions	LED drive ports	I/O ports: 8 pins (N, D version)
	Timers	Timer RA: 8 bits × 1 channel
		Timer RB: 8 bits × 1 channel
		(Each timer equipped with 8-bit prescaler)
		Timer RC: 16 bits × 1 channel
		(Input capture and output compare circuits)
		Timer RE: With real-time clock and compare match function
		(For J, K version, compare match function only.)
	Serial interfaces	2 channels (UART0, UART1)
		Clock synchronous serial I/O, UART
	Clock synchronous	1 channel
	serial interface	I ² C bus Interface ⁽¹⁾
		Clock synchronous serial I/O with chip select
	LIN module	Hardware LIN: 1 channel (timer RA, UART0)
	A/D converter	
		10-bit A/D converter: 1 circuit, 12 channels
	Watchdog timer	15 bits × 1 channel (with prescaler)
		Start-on-reset selectable
	Interrupts	Internal: 15 sources, External: 4 sources,
		Software: 4 sources, Priority levels: 7 levels
	Clock generation	3 circuits
	circuits	 XIN clock generation circuit (with on-chip feedback resistor)
		On-chip oscillator (high speed, low speed)
		High-speed on-chip oscillator has a frequency adjustment function
		 XCIN clock generation circuit (32 kHz) (N, D version)
		 Real-time clock (timer RE) (N, D version)
	Oscillation-stopped	XIN clock oscillation stop detection function
	detector	
	Voltage detection	On-chip
	circuit	
	Power-on reset circuit	On-chip
Electrical	Supply voltage	VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz) (other than K version)
Characteristics		VCC = 3.0 to 5.5 V (f(XIN) = 16 MHz) (K version)
2		VCC = 2.7 to 5.5 V (f(XIN) = 10 MHz)
		VCC = 2.2 to 5.5 V (f(XIN) = 5 MHz) (N, D version)
	Current consumption	Typ. 10 mA (VCC = 5.0 V , f(XIN) = 20 MHz)
	(N, D version)	Typ. 6 mA (VCC = 3.0 V , f(XIN) = 10 MHz)
		Typ. 2.0 μ A (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)
		Typ. 0.7 μ A (VCC = 3.0 V, stop mode)
	Programming and	VCC = 2.7 to 5.5 V
	erasure voltage	
Flash Memory		
Flash Memory		100 times
Flash Memory	Programming and	100 times
	Programming and erasure endurance	
	Programming and erasure endurance	-20 to 85°C (N version)
Operating Ambie	Programming and erasure endurance	

 Table 1.1
 Functions and Specifications for R8C/26 Group

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.

2. Specify the D, K version if D, K version functions are to be used.

1.6 Pin Functions

Table 1.5 lists Pin Functions.

Table 1.5Pin Functions

Туре	Symbol	I/O Type	Description	
Power supply input	VCC, VSS	I	Apply 2.2 to 5.5 V (J, K version are 2.7 to 5.5 V) to the VCC pin. Apply 0 V to the VSS pin.	
Analog power supply input	AVCC, AVSS	I	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.	
Reset input	RESET	I	Input "L" on this pin resets the MCU.	
MODE	MODE	I	Connect this pin to VCC via a resistor.	
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit Connect a ceramic resonator or a crystal oscillator between XIN and XOUT pins. To use an external clock input it to	
XIN clock output	XOUT	0		
XCIN clock input (N, D version)	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between the XCIN and XCOUT	
XCIN clock output (N, D version)	XCOUT	0	pins. To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.	
INT interrupt input	INTO, INT1, INT3	I	INT interrupt input pins	
Key input interrupt	KI0 to KI3	I	Key input interrupt input pins	
Timer RA	TRAO	0	Timer RA output pin	
	TRAIO	I/O	Timer RA I/O pin	
Timer RB	TRBO	0	Timer RB output pin	
Timer RC	TRCCLK	I	External clock input pin	
	TRCTRG	I	External trigger input pin	
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Sharing output-compare output / input-capture input / PWM / PWM2 output pins	
Timer RE	TREO	0	Timer RE output pin	
Serial interface	CLK0, CLK1	I/O	Clock I/O pin	
	RXD0, RXD1	I	Receive data input pin	
	TXD0, TXD1	0	Transmit data output pin	
I ² C bus interface	SCL	I/O	Clock I/O pin	
	SDA	I/O	Data I/O pin	
Clock synchronous	SSI	I/O	Data I/O pin	
serial I/O with chip	SCS	I/O	Chip-select signal I/O pin	
select	SSCK	I/O	Clock I/O pin	
	SSO	I/O	Data I/O pin	
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter	
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter	
I/O port	P0_0 to P0_7, P1_0 to P1_7, P3_1, P3_3 to P3_7, P4_5, P5_3, P5_4	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P1_0 to P1_7 also function as LED drive ports (N, D version).	
Input port	P4_2, P4_6, P4_7	I	Input-only ports	

I: Input O: Output I/O: Input and output

3. Memory

3.1 R8C/26 Group

Figure 3.1 is a Memory Map of R8C/26 Group. The R8C/26 group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM area is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM area is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

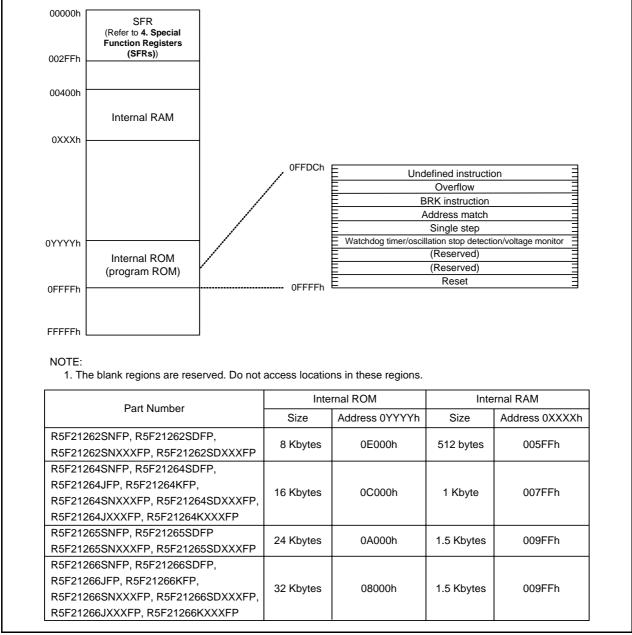


Figure 3.1 Memory Map of R8C/26 Group



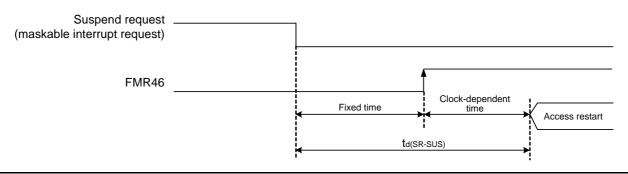


Figure 5.2 Time delay until Suspend

Table 5.6 Voltage Detection 0 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol	Falanelei	Condition	Min.	Тур.	Max.	Offic
Vdet0	Voltage detection level		2.2	2.3	2.4	V
-	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	-	0.9	-	μΑ
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽²⁾		-	-	300	μS
Vccmin	MCU operating voltage minimum value		2.2	-	-	V

NOTES:

- 1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
- 2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.

Table 5.7 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol	Farameter	Condition	Min.	Тур.	Max.	Unit
Vdet1	Voltage detection level ⁽⁴⁾		2.70	2.85	3.00	V
-	Voltage monitor 1 interrupt request generation time ⁽²⁾		-	40	-	μS
-	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	-	0.6	-	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		-	-	100	μS

NOTES:

- 1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
- 2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes Vdet1.
- 3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

4. This parameter shows the voltage detection level when the power supply drops. The voltage detection level when the power supply rises is higher than the voltage detection level when the power supply drops by approximately 0.1 V.

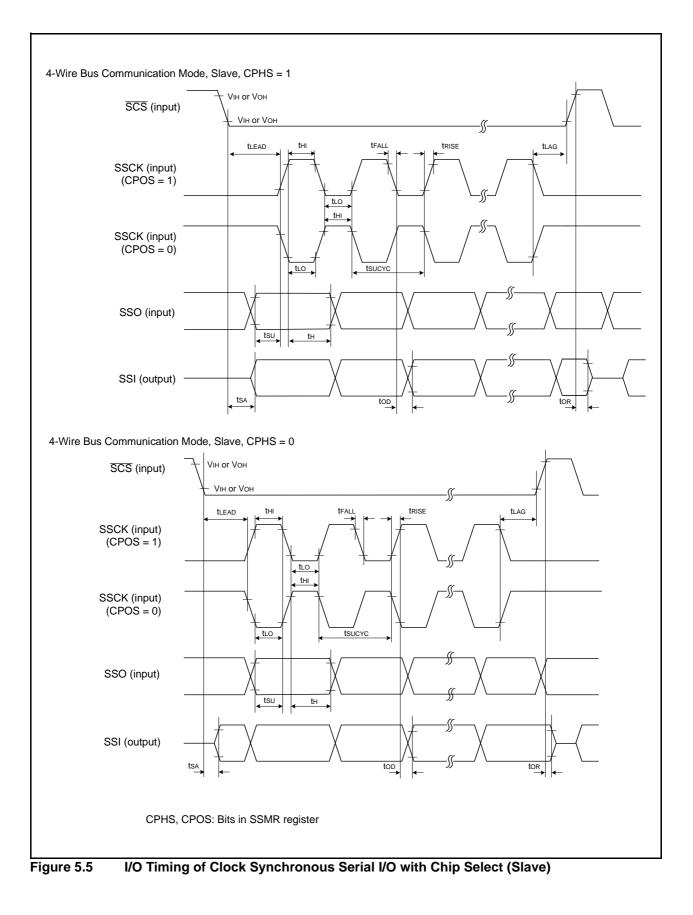
Table 5.8 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Baramatar	detection level		Standard			
Symbol	Farameter	Condition	Min.	Тур.	Max.	Unit	
Vdet2	Voltage detection level		3.3	3.6	3.9	V	
-	Voltage monitor 2 interrupt request generation time ⁽²⁾		-	40	-	μS	
-	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	-	0.6	-	μA	
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		-	-	100	μs	

NOTES:

- 1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
- 2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
- 3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.





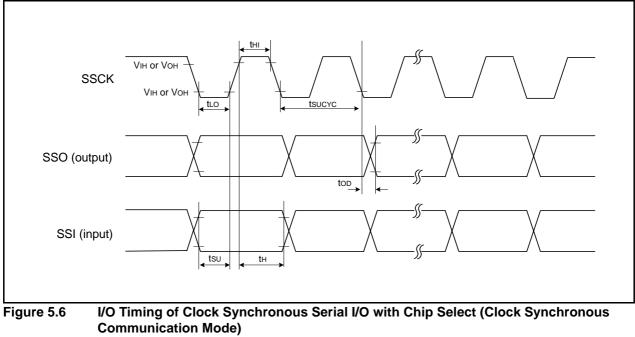


Table 5.16Electrical Characteristics (2) [Vcc = 5 V]
(Topr = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Paramotor		Condition		Standar	ł	Unit
Symbol	Parameter			Min.	Тур.	Max.	Unit
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open,	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	10	17	mA
	other pins are Vss		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	9	15	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	6	-	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	5	-	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	4	-	mA
	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	2.5	_	mA		
	High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	_	10	15	mA	
			XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	4	_	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	_	5.5	10	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	2.5	-	mA
	Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	_	130	300	μA	
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	_	130	300	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	_	30	-	μA

Timing Requirements (Unless Otherwise Specified: Vcc = 5 V, Vss = 0 V at Topr = 25°C) [Vcc = 5 V]

Table 5.18 XIN Input, XCIN Input

Symbol	Parameter	Stan	Unit	
Symbol	Falanletei	Min.	Max.	Unit
tc(XIN)	XIN input cycle time	50	-	ns
twh(xin)	XIN input "H" width	25	-	ns
twl(XIN)	XIN input "L" width	25	-	ns
tc(XCIN)	XCIN input cycle time	14	-	μS
twH(XCIN)	XCIN input "H" width	7	-	μS
twl(xcin)	XCIN input "L" width	7	_	μS

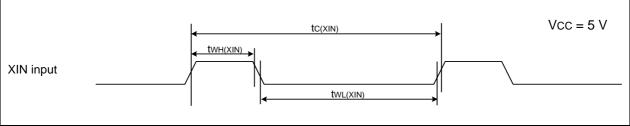


Figure 5.8 XIN Input and XCIN Input Timing Diagram when Vcc = 5 V

Table 5.19 TRAIO Input

Symbol	Parameter		Standard		
Symbol	Falanielei	Min.	Max.	Unit	
tc(TRAIO)	TRAIO input cycle time	100	-	ns	
twh(traio)	TRAIO input "H" width	40	-	ns	
twl(traio)	TRAIO input "L" width	40	-	ns	

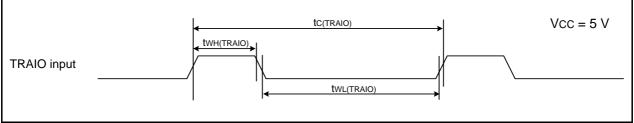


Figure 5.9 TRAIO Input Timing Diagram when Vcc = 5 V

Symbol	Parameter		Standard		
Symbol	Falallelel	Min.	Max.	Unit	
tc(CK)	CLKi input cycle time	200	-	ns	
tW(CKH)	CLKi input "H" width	100	-	ns	
tW(CKL)	CLKi input "L" width	100	-	ns	
td(C-Q)	TXDi output delay time	-	50	ns	
th(C-Q)	TXDi hold time	0	-	ns	
tsu(D-C)	RXDi input setup time	50	-	ns	
th(C-D)	RXDi input hold time	90	-	ns	

i = 0 or 1

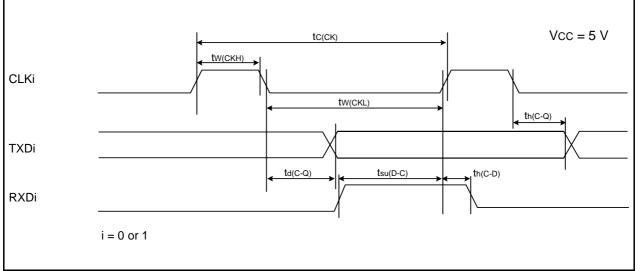


Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V

Table 5.21External Interrupt INTi (i = 0, 1, 3) Input

Symbol	Parameter		Standard		
Symbol	Falanielei	Min.	Max.	Unit	
tw(INH)	INTi input "H" width	250(1)	-	ns	
tw(INL)	INTi input "L" width	250 ⁽²⁾	-	ns	

NOTES:

1. When selecting the digital filter by the INTi input filter select bit, use an INTi input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

2. When selecting the digital filter by the INTi input filter select bit, use an INTi input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

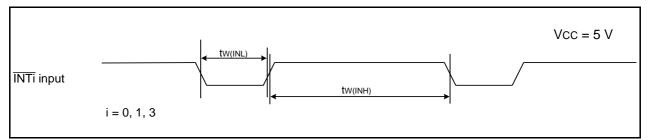


Figure 5.11 External Interrupt INTi Input Timing Diagram when Vcc = 5 V

Table 5.29Electrical Characteristics (6) [Vcc = 2.2 V]
(Topr = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol Parameter		Condition		Standard			Unit
Symbol	Parameter		Condition	Min.	Тур.	Max.	Unit
Icc	Power supply current (Vcc = 2.2 to 2.7 V) Single-chip mode, output pins are open,	High-speed clock mode	XIN = 5 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	3.5	-	mA
	other pins are Vss		XIN = 5 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.5	-	mA
		High-speed on-chip oscillator	XIN clock off High-speed on-chip oscillator on fOCO = 5 MHz Low-speed on-chip oscillator on = 125 kHz No division	-	3.5	-	mA
		mode	XIN clock off High-speed on-chip oscillator on fOCO = 5 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.5	-	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	-	100	230	μΑ
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	-	100	230	μΑ
		XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	-	25	_	μΑ	
	Ī	Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	22	60	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	20	55	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (high drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	3.0	_	μΑ
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (low drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	1.8	_	μA
		Stop mode	XIN clock off, $T_{opr} = 25^{\circ}C$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	0.7	3.0	μA
			XIN clock off, $T_{opr} = 85^{\circ}C$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	1.1	_	μA

Symbol	Parameter		Conditions	Standard			Unit
Symbol		Farameter	Conditions	Min.	Тур.	Max.	Unit
_	Resolution		Vref = AVCC	-	-	10	Bits
-	Absolute	10-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 5.0 V	-	-	±3	LSB
	accuracy	8-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 5.0 V	-	-	±2	LSB
		10-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 3.3 V	-	-	±5	LSB
		8-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 3.3 V	-	_	±2	LSB
Rladder	Resistor ladder		Vref = AVCC	10	_	40	kΩ
tconv	Conversion time	10-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 5.0 V	3.3	_	-	μS
		8-bit mode	ϕ AD = 10 MHz, Vref = AVCC = 5.0 V	2.8	_	-	μS
Vref	Reference voltag	e		2.7	_	AVcc	V
Via	Analog input volta	age ⁽²⁾		0	-	AVcc	V
-	A/D operating	Without sample and hold		0.25	_	10	MHz
	clock frequency	With sample and hold		1	_	10	MHz

Table 5.36 A/D Converter Characteristics

NOTES:

1. AVcc = 2.7 to 5.5 V at T_{opr} = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.

2. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

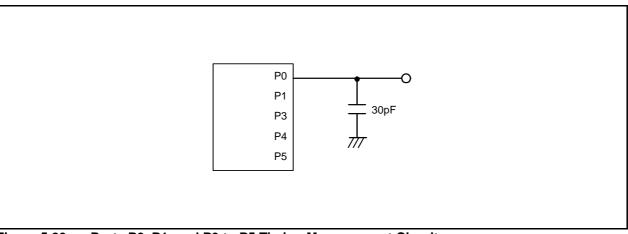


Figure 5.20 Ports P0, P1, and P3 to P5 Timing Measurement Circuit

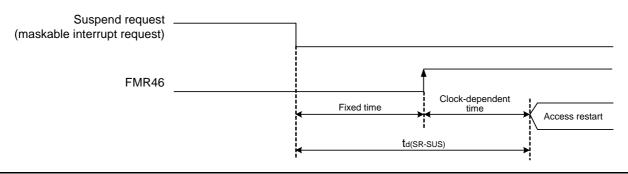


Figure 5.21 Time delay until Suspend

Table 5.39 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol	Faianielei	Condition	Min.	Тур.	Max.	Offic
Vdet1	Voltage detection level ^(2, 4)		2.70	2.85	3.0	V
td(Vdet1-A)	Voltage monitor 1 reset generation time ⁽⁵⁾		-	40	200	μS
-	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	-	0.6	-	μΑ
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		-	-	100	μS
Vccmin	MCU operating voltage minimum value		2.70	_	_	V

NOTES:

1. The measurement condition is Vcc = 2.7 to 5.5 V and $T_{opr} = -40$ to $85^{\circ}C$ (J version) / -40 to $125^{\circ}C$ (K version).

2. Hold Vdet2 > Vdet1.

3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

4. This parameter shows the voltage detection level when the power supply drops.

- The voltage detection level when the power supply rises is higher than the voltage detection level when the power supply drops by approximately 0.1 V.
- 5. Time until the voltage monitor 1 reset is generated after the voltage passes Vdet1 when Vcc falls. When using the digital filter, its sampling time is added to td(Vdet1-A). When using the voltage monitor 1 reset, maintain this time until Vcc = 2.0 V after the voltage passes Vdet1 when the power supply falls.

Table 5.40 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol	Falanetei	Condition	Min.	Тур.	Max.	Unit
Vdet2	Voltage detection level ⁽²⁾		3.3	3.6	3.9	V
td(Vdet2-A)	Voltage monitor 2 reset/interrupt request generation time ^(3, 5)		-	40	200	μS
-	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	-	0.6	-	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽⁴⁾		-	-	100	μS

NOTES:

1. The measurement condition is Vcc = 2.7 to 5.5 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version).

2. Hold Vdet2 > Vdet1.

3. Time until the voltage monitor 2 reset/interrupt request is generated after the voltage passes Vdet2.

- 4. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.
- 5. When using the digital filter, its sampling time is added to td(Vdet2-A). When using the voltage monitor 2 reset, maintain this time until Vcc = 2.0 V after the voltage passes Vdet2 when the power supply falls.

Cumhal	Parameter		Conditions		Stand	Unit	
Symbol	Paramete	er	Conditions	Min.	Тур.	Max.	
tsucyc	SSCK clock cycle tim	e		4	-	_	tCYC ⁽²⁾
tнı	SSCK clock "H" width	1		0.4	-	0.6	tsucyc
tlo	SSCK clock "L" width			0.4	-	0.6	tsucyc
trise	SSCK clock rising	Master		-	-	1	tCYC ⁽²⁾
time	time	Slave		-	-	1	μS
tfall	SSCK clock falling time	Master		-	-	1	tCYC ⁽²⁾
		Slave		-		1	μS
ts∪	SSO, SSI data input	setup time		100	-	_	ns
tн	SSO, SSI data input	hold time		1	-	-	tCYC ⁽²⁾
t LEAD	SCS setup time	Slave		1tcyc + 50	1		ns
tlag	SCS hold time	Slave		1tcyc + 50	_	-	ns
top	SSO, SSI data outpu	t delay time		-	-	1	tCYC ⁽²⁾
tSA	SSI slave access time			-	_	1.5tcyc + 100	ns
tor	SSI slave out open time			-	-	1.5tcyc + 100	ns

Table 5.45 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

NOTES:

1. Vcc = 2.7 to 5.5 V, Vss = 0 V at T_{opr} = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified. 2. $1t_{CYC} = 1/f1(s)$



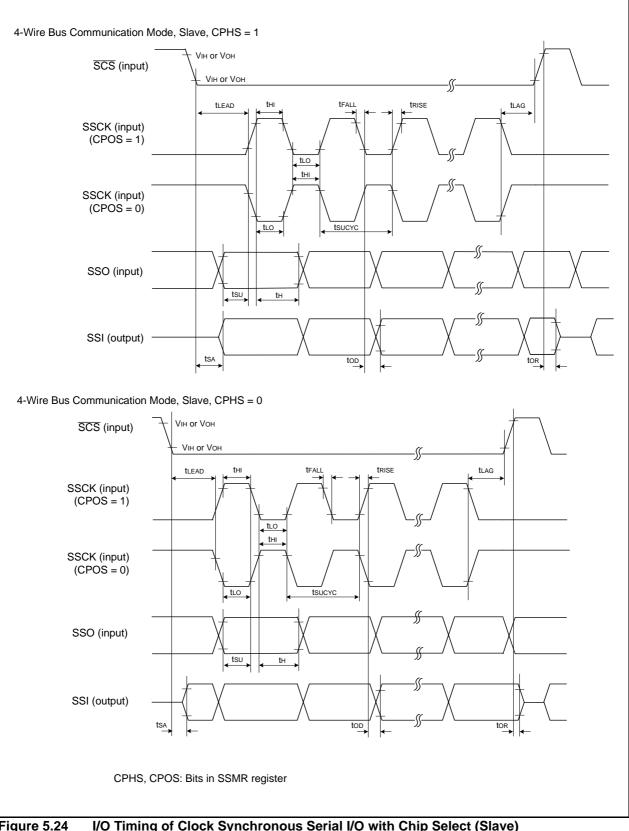


Figure 5.24 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

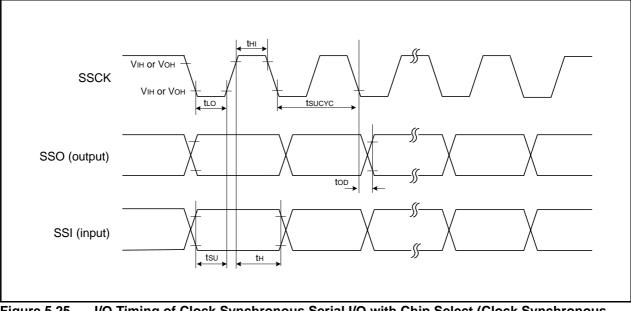


Figure 5.25 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.46 Ti	iming Requirements	of I ² C bus Interface ⁽¹⁾
---------------	--------------------	--

Symbol	Parameter	Condition	Sta	Unit		
Symbol	Parameter	Condition	Min.	Тур.	Max.	
tSCL	SCL input cycle time		12tcyc + 600 ⁽²⁾	-	-	ns
t SCLH	SCL input "H" width		3tcyc + 300 ⁽²⁾	-	-	ns
tSCLL	SCL input "L" width		5tcyc + 500 ⁽²⁾	-	_	ns
tsf	SCL, SDA input fall time		-	-	300	ns
tSP	SCL, SDA input spike pulse rejection time		-	-	1tcyc ⁽²⁾	ns
tbuf	SDA input bus-free time		5tcyc ⁽²⁾	-	-	ns
t STAH	Start condition input hold time		3tcyc ⁽²⁾	-	-	ns
t STAS	Retransmit start condition input setup time		3tCYC ⁽²⁾	-	-	ns
t STOP	Stop condition input setup time		3tcyc ⁽²⁾	-	-	ns
tsdas	Data input setup time		1tcyc + 20 ⁽²⁾	-	-	ns
t SDAH	Data input hold time		0	-	-	ns

NOTES:

1. Vcc = 2.7 to 5.5 V, Vss = 0 V at Topr = -40 to 85° C (J version) / -40 to 125° C (K version), unless otherwise specified.

2. 1tcyc = 1/f1(s)

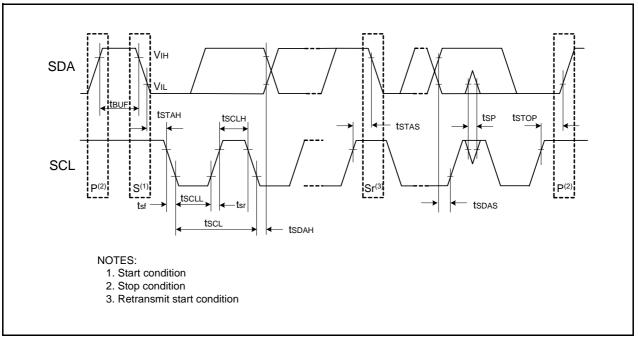


Figure 5.26 I/O Timing of I²C bus Interface

Table 5.54Electrical Characteristics (4) [Vcc = 3 V]
(Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.)

Symbol Parameter	Parameter	Parameter Condition		Standard			Unit
Symbol				Min.	Тур.	Max.	Unit
Icc	Power supply current (Vcc = 2.7 to 3.3 V) Single-chip mode, output pins are open,	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	6	_	mA
	other pins are Vss		XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	2	-	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	_	5	9	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	2	_	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	-	130	300	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	25	70	μΑ
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	-	23	55	μΑ
		Stop mode	XIN clock off, $T_{opr} = 25^{\circ}C$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	0.7	3.0	μA
			XIN clock off, $T_{opr} = 85^{\circ}C$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	1.1	_	μA
			XIN clock off, Topr = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	3.8	_	μA

Symbol	Parameter		Standard		
Symbol	Faianelei	Min.	Max.	Unit	
tc(CK)	CLKi input cycle time	300	-	ns	
tw(CKH)	CLKi input "H" width	150	-	ns	
tW(CKL)	CLKi Input "L" width		-	ns	
td(C-Q)	TXDi output delay time	-	80	ns	
th(C-Q)	TXDi hold time	0	-	ns	
tsu(D-C)	RXDi input setup time		-	ns	
th(C-D)	RXDi input hold time	90	-	ns	

i = 0 or 1

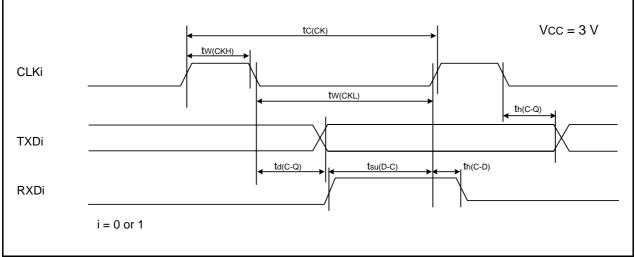




Table 5.58 External Interrupt INTi (i = 0, 1, 3) Input

Symbol	Parameter	Stan	dard	Unit
Symbol	Falameter		Max.	Unit
tw(INH)	INTi input "H" width	380(1)	-	ns
tw(INL)	INTi input "L" width	380(2)	1	ns

NOTES:

1. When selecting the digital filter by the INTi input filter select bit, use an INTi input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

2. When selecting the digital filter by the INTi input filter select bit, use an INTi input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

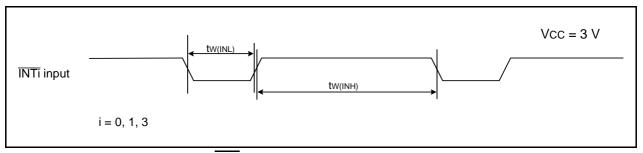
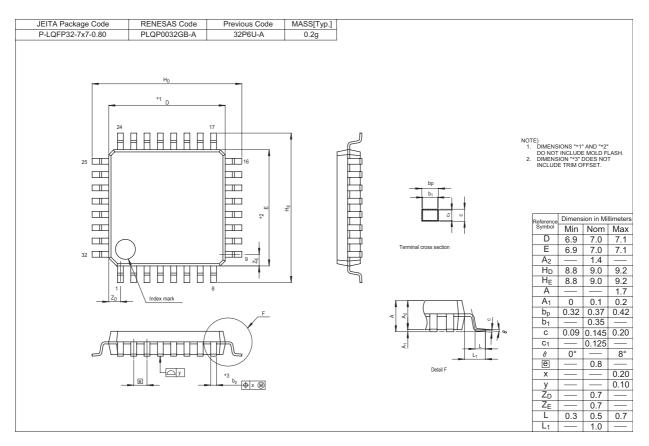


Figure 5.34 External Interrupt INTi Input Timing Diagram when Vcc = 3 V

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the "Packages" section of the Renesas Technology website.



REVISION HISTORY

R8C/26 Group, R8C/27 Group Datasheet

Rev.	Date		Description
Rev.	Dale	Page	Summary
1.30	May 25, 2007	16	Figure 3.2 part number revised
		30	Table 5.10 revised
		53	Table 5.39 NOTE4 added
		55	Table 5.42 revised
1.40a	Jun 14, 2007	5, 7	Table 1.3 and Table 1.4 revised
2.00	Mar 01, 2008	1, 49	1.1, 5.2 "J and K versions are" deleted
		5, 7	Table 1.3, Table 1.4 revised
		11	Table 1.6 NOTE3 added
		15, 16	Figure 3.1, Figure 3.2; "Expanded area" deleted
		17	Table 4.1 "002Ch" added
		18	Table 4.2 "0036h"; J, K version "0100X000b" → "0100X001b"
		24, 49	Table 5.2, Table 5.35; NOTE2 revised
		30	Table 5.10 revised, NOTE4 added
2.10	Sep 26, 2008	_	"RENESAS TECHNICAL UP DATE" reflected: TN-16C-A172A/E
		26, 51	Table 5.4, Table 5.37 NOTE2, NOTE4 revised
		27, 52	Table 5.5, Table 5.38 NOTE2, NOTE5 revised
		53	Table 5.39 Parameter: Voltage monitor 1 reset generation time added NOTE5 added
			Table 5.40 revised
		54	Table 5.41 revised Figure 5.22 revised

All trademarks and registered trademarks are the property of their respective owners.